Jaime Rodriguez –T02

Weekly Progress Report

Nov. 23rd 2014

This Week:

1. Combined and formatted homework 5.
2. Created plan and test case for Reliability module for homework 6.
3. Assembled PCB with components using reflow oven and verified functionality.
4. Created prototype of enclosure for board, and adjusted dimensions accordingly.

Next Week:

1. Create final enclosure for PCB.
2. Assemble full circuit with system in a box for project presentation
3. Begin preparing for presentation.